

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
KWANG HOON LEE	07/11/2014
HYUNG-CHAN KIM	07/09/2014
SANG YEUL HAN	07/09/2014
SEOK KYUN KIM	07/14/2014
KYUNG EUN KIM	07/09/2014
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SAMSUNG ELECTRONICS CO., LTD.
<b>Street Address:</b>	129, SAMSUNG-RO, YEONGTONG-GU
<b>City:</b>	SUWON-SI, GYEONGGI-DO
<b>State/Country:</b>	REPUBLIC OF KOREA
<b>Postal Code:</b>	443-742
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14336812
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	716812
<b>NAME OF SUBMITTER:</b>	JOHN L. GASE
<b>SIGNATURE:</b>	/John L. Gase/
<b>DATE SIGNED:</b>	07/21/2014
<b>Total Attachments: 3</b>	
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## ASSIGNMENT

WHEREAS, I/WE

Kwang Hoon Lee, Hyung-Chan Kim, Sang Yeul Han, Seok Kyun Kim, and Kyung Eun Kim all c/o Samsung Advanced Institute of Technology, San 14-1 Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do, KR,

hereinafter referred to as Assignor, have invented a certain invention entitled:

FUSION POLYPEPTIDE INHIBITING VEGF-C, VEGF-D AND/OR ANGIOPOIETIN-2,  
AND USE THEREOF

for which invention an application (provisional or non-provisional) for a U.S. patent was filed on July 21, 2014, under U.S. Application No. 14/336,812, and

WHEREAS, SAMSUNG ELECTRONICS CO., LTD. of 129, Samsung-ro, Yeongtong-gu, Suwon-si, Gyeonggi-do, 443-742, KR, hereinafter referred to as Assignee, is desirous of acquiring the entire right, title, and interest in, to, and under the invention described in the patent application, including the entire priority right derived from the application,

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged,

Assignor assigns and transfers to Assignee and Assignee's legal representatives, successors, and assigns the entire right, title, and interest in, to, and under the invention, the referenced patent application, and other such applications (e.g., provisional applications, non-provisional applications, continuations, continuations-in-part, divisionals, reissues, reexaminations, national and regional phase applications, petty patent applications, and utility model applications) that may be filed in the U.S. and/or any country foreign to the U.S. on the invention, and the patents that may issue thereon,

Assignor conveys to the Assignee the right to make applications in Assignee's own behalf for protection of the invention in the U.S. and countries foreign to the U.S. and to claim priority to the referenced patent application and other such applications that may be filed in the U.S. or any country foreign to the U.S. on the invention under the Patent Cooperation Treaty, the Paris Convention, and any other international arrangements,

Assignor will not execute any writing or do any act conflicting with the terms of this assignment,

Assignor will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to pursue the patent applications identified herein, including, but not limited to, rendering all necessary assistance in making applications for and obtaining patents that may issue thereon in the U.S. and any countries foreign to the U.S. on the invention, and in enforcing any rights accruing as a result of such applications or patents, by, for example, executing statements and other affidavits,

Assignor and Assignee agree the terms of this assignment shall bind, and inure to the benefit of, the legal representatives, successors, and assigns of all parties hereto,

Assignor authorizes Assignee to insert in this assignment the number and filing date of the application if the number and filing date of the application are not recited herein at the time of execution of this assignment by any or all of the parties hereto,

Assignor and Assignee agree that U.S. law governs this assignment, and

Assignee acknowledges and accepts this assignment.

IN WITNESS WHEREOF, Assignor has hereunder set his/her hand on the date shown below.

Date 07/11/2014 Lee  
Assignor: Kwang Hoon Lee

=====  
Date 07/09/2014 Hyung-Chan Kim  
Assignor: Hyung-Chan Kim

=====  
Date 07/09/2014 Sang Yeul Han  
Assignor: Sang Yeul Han

=====  
Date 07/14/2014 Seok Kyun Kim  
Assignor: Seok Kyun Kim

In re Appln. Of Lee et al.

Attorney Docket No. 716812  
Client Reference No. OPF20123092US/RG2012070111US0

Date 2014 / 07 / 09

  
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Assignor: Kyung Eun Kim

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